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BNS-OD-FC001/A4

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LED DISPLAY LTS-2807CKD-P

LED DISPLAY

LTS-2807CKD-P

<u>Rev</u>	Description	By	<u>Date</u>			
01	Preliminary Spec.	Reo Lin	02/08/2013			
02	Revised error for packing spec. in page 9	Reo Lin	10/21/2013			
	Above data for PD and Customer tracking only					
-	NPPR Received and Upload on System	Reo Lin	10/21/2013			
А	Modify symbol location in page 3	Reo Lin	06/26/2014			





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1. Description

The LTS-2807CKD-P is a 0.2 inch (5.08mm) digit height single digit SMD display. This device uses AS-AllnGap hyper red chips(AllnGap epi on GaAs substrate). The display has gray face and white segments.

1.1 Features

- 0.2 inch (5.08 mm) DIGIT HEIGHT
- CONTINUOUS UNIFORM SEGMENTS
- LOW POWER REQUIREMENT
- EXCELLENT CHARACTERS APPEARANCE
- HIGH BRIGHTNESS & HIGH CONTRAST
- WIDE VIEWING ANGLE
- SOLID STATE RELIABILITY
- CATEGORIZED FOR LUMINOUS INTENSITY.
- LEAD-FREE PACKAGE(ACCORDING TO ROHS)

1.2 Device

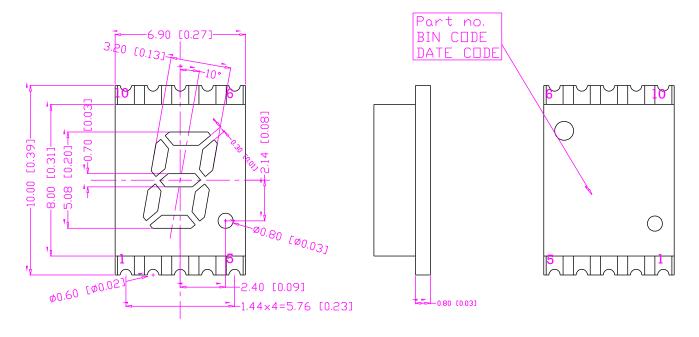
Part No	Description
AllnGap Hyper Red	Common Anode
LTS-2807CKD-P	Rt. Hand Decimal





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2. Package Dimensions





Notes :

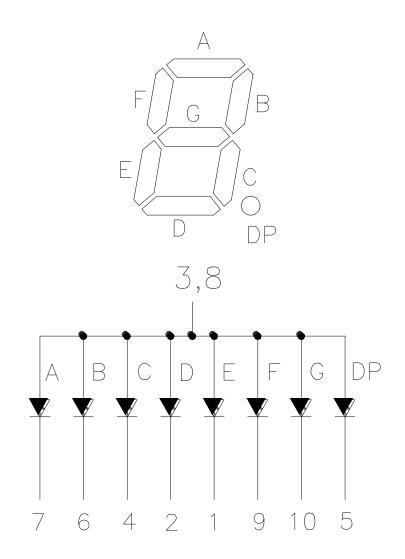
- 1. All dimensions are in millimeters. Tolerances are ± 0.25 mm (0.01") unless otherwise noted
- 2. Foreign material on segment ≤ 10 mil
- 3. Ink contamination (surface) *≦*20mils
- 4. Bubble in segment ≤ 10 mil
- 5. Bending \leq 1% of reflector length
- 6. Plastic pin's burr max is 0.05 mm





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3. Internal Circuit Diagram







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4. Pin Connection

Νο	Connection
1	CATHODE E
2	CATHODE D
3	COMMON ANDOE
4	CATHODE C
5	CATHODE DP
6	CATHODE B
7	CATHODE A
8	COMMON ANODE
9	CATHODE F
10	CATHODE G





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5. Rating and Characteristics

5.1. Absolute Maximum Rating at Ta=25°C

Parameter	Maximum Rating	Unit	
Power Dissipation Per Segment	70	mW	
Peak Forward Current Per Segment (1/10 Duty Cycle, 0.1ms Pulse Width)	60	mA	
Continuous Forward Current Per Segment	25	mA	
Derating Linear From 25°C Per Segment	0.28	mA/°C	
Operating Temperature Range	-35°C to +105°C		
Storage Temperature Range	-35°C to +105°C		

Iron Soldering Conditions: 1/16 inch Below Seating Plane for 3 Seconds at 260 $^\circ\text{C}$

5.2. Electrical / Optical Characteristics at Ta=25°C

Parameter	Symbol	MIN.	TYP.	MAX.	Unit	Test Condition
Average Luminous Intensity Per Segment	IV	201	650		μcd	IF=1mA
Average Luminous intensity Fer Segment	IV		8250			IF=10mA
Peak Emission Wavelength	λр		650		nm	IF=20mA
Spectral Line Half-Width	Δλ		20		nm	IF=20mA
Dominant Wavelength	λd		639		nm	IF=20mA
Forward Voltage Per Chip	VF		2.05	2.6	V	IF=20mA
Reverse Current Per Segment ⁽²⁾	IR			100	μA	VR=5V
Luminous Intensity Matching Ratio (Similar Light Area)	IV-m			2:1		IF=1mA

Notes :

- 1. Luminous intensity is measured with a light sensor and filter combination that approximates the CIE (Commission International De L'Eclariage) eye-response curve
- 2. Reverse voltage is only for IR test. It cannot continue to operate at this situation
- 3. Cross talk specification $\,\leq\,$ 2.5%



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5.3. Typical Electrical / Optical Characteristics Curves (25°C Ambient Temperature Unless Otherwise Noted)

KD 100 RELATIVE INTENSITY (%) 50 0 500 550 600 750 800 650 700 PEAK WAVELENGTH λp (nm) Fig1.Spectral Emission KD 160 4 140 KD 0± 0[.] 5 10 15 20 25 FORWARD CURRENT, If (mA) 1.0 2.0 3.0 4.0 FORWARD VOLTAGE, Vf (Volts) 30 5.0 Fig2. Forward Current vs. Fig3. Relative Luminous Intensity Forward Voltage vs. DC Forward Current 40 1000 (Fm) 35 05 Current-mA 20, 20 PEAK CURRENT, Ipeak (n 001 002 002 002 002 002 음15 5 ľ 10 0 10 20 30 40 50 60 70 80 90 100 110 Ambient Temperature (TA)-°C 0 2 5 10 20 50 DUTY CYCLE % (Frequency 1Khz) 5 10 20 100 1 Fig5. MAX. ALLOWABLE DC CURRENT Fig5. Maximum Peak Current VS. AMBIENT TEMPERATURE. vs. Duty Cycle %

NOTE : KD=AlInGaP HYPER RED

Part No. : LTS-2807CKD-P BNS-OD-FC002/A4

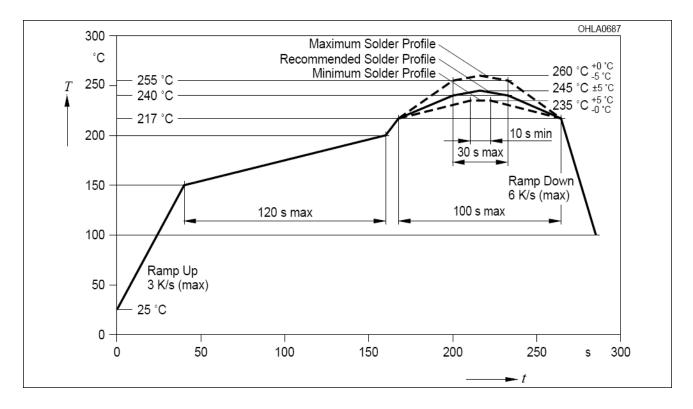
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6. SMT SOLDERING INSTRUCTION

(Number of reflow process shall be less than 2 times, and cooling process to normal temperature is required between the first and the second soldering process)



Notes :

1. Recommended soldering condition

Reflow Soldering (Two times only)		Soldering Iron (One time only)		
Pre-heat:	120~150°C.	Temperature	300°C Max.	
Pre-heat time:	120sec. Max.	Soldering time	3sec. Max.	
Peak temperature:	260°C Max.			
Soldering time:	5sec. Max.			

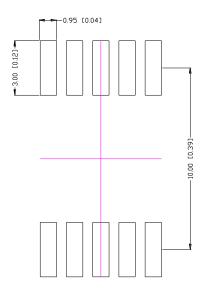
2. Number of reflow process shall be less than 2 times, and cooling process to normal temperature is required between the first and the second soldering process.

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7. Recommended Soldering Pattern



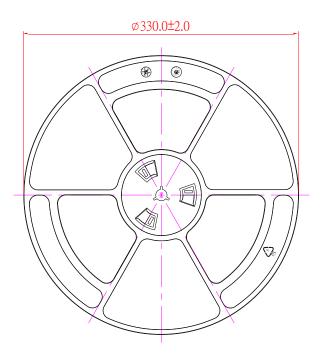


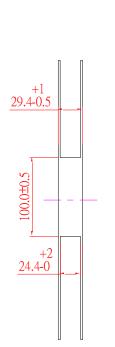


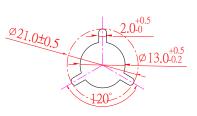
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8. Packing Specification

8.1. Packing Reel Dimensions





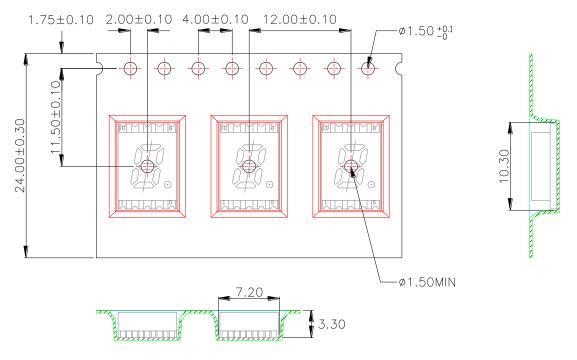






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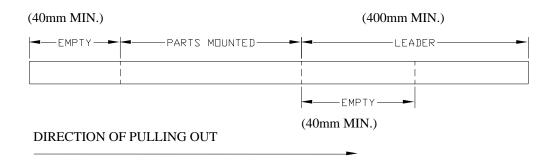
8.2. Packing Carrier Dimensions

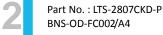


- 1. 10 sprocket hole pitch cumulative tolerance ±0.20.
 2. Carrier camber is within 1 mm in 250 mm.
 3. Material : Black Conductive Polystyrene Alloy.
 4. All dimensions meet EIA-481-D requirements.

- 5. Thickness : 0.30±0.05mm.
- 6. Packing length per 22" reel : 56.5 Meters.(1:3)7. Component load per 13" reel : 1000 pcs.

8.3.Trailer part / Leader part





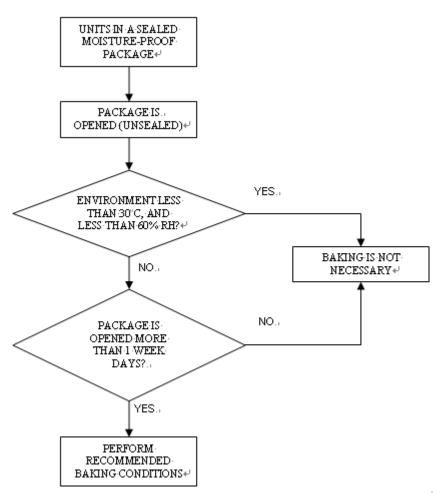
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9. Moisture Proof Packing

All N/D SMD displays are shipped in moisture proof package. The displays should be stored at 30°C or less and60% RH or less. Once the package opened, moisture absorption begins.



If the parts are not stored in dry conditions, they must be baked before reflow to prevent damage to the parts. Baking should only be done once

Package	Temperature	Time
In Reel	60°C	≧48hours
In Bulk	100°C	\geq 4hours
	125°C	≥2hours

